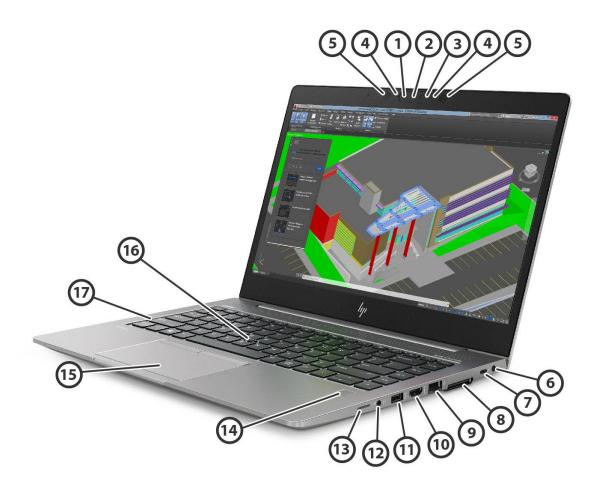
Overview

HP ZBook 14u G5 Mobile Workstation



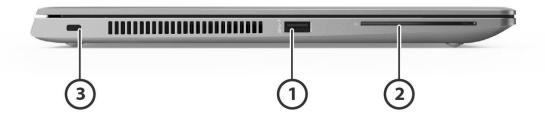
- 1. HD Camera (Select models only)
- 2. IR Camera (Select models only)
- 3. Webcam LED (Select models only)
- 4. Internal microphones
- 5. IR Camera LEDs (Select models only)
- 6. Power connector
- 7 USB Type-C™ with Thunderbolt™
- 8. Docking connector
- 9. Ethernet port

Front

- 10. HDMI port (Cable not included)
- 11. USB 3.1 Gen 1 port
- 12. Audio combo jack
- 13. SIM card slot¹
- 14. Fingerprint reader
- 15. Clickpad
- 16. Pointstick
- 17. HP Collaboration Keyboard

¹All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug

Overview



Left

- 1. 1 USB 3.0 (charging)
- 2. 1 smart card reader
- 3. Security lock slot

Overview

At A Glance

- Eye-catching ultraslim design, premium precision-crafted machined aluminum (CNC), seamless formed aluminum chassis for clean, crisp, premium look and feel
- .
- Designed to pass 14 MIL-STD-810G tests*.
- Workstation-caliber AMD Radeon Pro[™] discrete graphics: AMD Radeon Pro[™] WX3100 (2 GB dedicated GDDR5); AMD Enduro[™] graphics technology.
- Intel® Integrated graphics: Intel® HD Graphics 620 integrated on 7th Generation Intel Core processors. Intel® UHD Graphics 630 integrated on 8th Generation Intel Core processors.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- Choice of dual core 7th generation Intel® Core™ i5 or quad core 8th generation Intel® Core™ i7 and i5 processors
- Intel® Core™ i7 with vPro™ and Core™ i5 with vPro™ technology (optional)
- HP Performance Advisor for optimal configuration, compatibility and performance
- Up to two SODIMMs supporting up to 32 GB DDR4-2400 MHz dual channel memory.
- Supports up to 3 independent displays via internal LCD Panel, system DisplayPort™, system VGA, or using the HP UltraSlim Docking Station or HP Thunderbolt Docking Station. Supports DisplayPort™ 1.2 monitors.
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke. HP Spill Resistant Collaboration Keyboard with Durakeys, touchpad buttons with Duracoat finish. Backlight keyboard in full aluminum deck with magnesium bottom reinforcement, chemically strengthened glass touchpad, and updated system functions indicators. 2 discrete buttons with LED indicator for convenient one touch access: Wireless On/Off, Volume Mute Bang and Olufsen audio optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal-clear dialog without distortion at high volume, and new discrete amp.HP Long life battery solution: 3-cell (50 WHr) supporting HP Fast Charge

•

- 14-inch diagonal LED-backlit display:
 - o FHD IPS eDP anti-glare, 67% sRGB at 220 nits (1920x1080)
 - o FHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (1920x1080)
 - UHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (3840x 2160)
 - FHD IPS eDP touch screen with Corning Gorilla Glass 3, 67% sRGB at 220 nits (1920x1080)
 - HP SureView Integrated Privacy Display FHD IPS eDP + PSR touch screen with Corning Gorilla Glass 3, 100% sRGB at 700 nits with ambient light sensor Touch (1920x1080)
- Wireless connectivity options:
 - Intel® Dual Band Wireless-AC 8265 802.11 AC (2x2) WiFi and Bluetooth 4.2 combo adaptor (vPro™)
 - Intel® Dual Band Wireless-AC 8265 802.11 AC (2x2) WiFi and Bluetooth 4.2 combo adaptor (non-vPro™)
 - o Realtek RTL8822BE 802.11ac 2x2 Wi-Fi and Bluetooth 4.2 combo adapter
 - Optional integrated wireless 4G (LTE) mobile broadband module support
- One dedicated drive slots. (1) M.2 slot support up to 2 TB of storage
- Enterprise grade security with HP SureStart Gen4, HP Privacy Camera3, HP Sure View2, HP Sure Run, HP Sure Recover, and Fingerprint reader2
- Low halogen, ENERGY STAR® certified and EPEAT® TBD registered in the U.S. EPEAT® status varies by country- please see epeat.net.

* MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled OS Windows 10 Pro 64*

Windows 10 Home 64*

Windows 10 Home 64 Advanced*

FreeDOS 2.0

Supported OS Windows 10 Enterprise 64*

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

PROCESSOR*

7th Generation Intel® Core™ i5 7300U vPro™ with Intel® HD 620 graphics (2.6 GHz, 3 MB cache, 2 cores) * Up to 3.5 GHz with Intel® Turbo Boost Technology

7th Generation Intel® Core™ i5 7200U with Intel® HD 620 graphics (2.5 GHz, 3 MB cache, 2 cores) * Up to 3.1 GHz with Intel® Turbo Boost Technology

8th Generation Intel® Core™ i7 8650U vPro™ with Intel® UHD 630 graphics (1.9 GHz, 8 MB cache, 4 cores) * Up to 4.2 GHz with Intel® Turbo Boost Technology

8th Generation Intel® Core™ i7 8550U with Intel® UHD 630 graphics (1.8 GHz, 8 MB cache, 4 cores) * Up to 4.0 GHz with Intel® Turbo Boost Technology

8th Generation Intel® Core™ i5 8350U vPro™ with Intel® HD 620 graphics (1.7 GHz, 6 MB cache, 4 cores) * Up to 3.6 GHz with Intel® Turbo Boost Technology

8th Generation Intel® Core™ i5 8250U with Intel® UHD 630 graphics (1.6 GHz, 6 MB cache, 4 cores) * Up to 3.4 GHz with Intel® Turbo Boost Technology

* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Also note that the Intel® Turbo Boost is based on max GHz for a single core.



Features

CHIPSET

Intel® Kaby Lake Chipset integrated with 7th Generation processor Intel® Kaby Lake – R Chipset integrated with 8th Generation processor

INTEL® CORE™ 15 WITH VPRO/CORE 17 WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™ and Core™ i7 with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update mobile workstations regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology, such as Intel Active Management technology and Intel Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Intel® HD 620 Graphics*
Intel® UHD 630 Graphics**

AMD Radeon Pro™ WX3100 (2 GB dedicated GDDR5) ***

Microsoft DirectX® 12 (Shader Model 5.0) and OpenGL® 4.3capable

AMD Enduro™ Technology supported.

- * HD content required to view HD images; only available on 7Th Generation Intel® processors
- ** UHD content required to view UHD images; only available on 8th Generation Intel® processors
- *** Supports up to 3 independent displays via internal LCD Panel, system DisplayPort™, system VGA, or using the HP UltraSlim Docking Station DisplayPort™ and VGA ports (sold separately).

DISPLAY

- Internal
 - 14.0" diagonal FHD IPS eDP anti-glare, 67% sRGB at 220 nits (1920x1080)
- 14.0" diagonal FHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (1920x1080)
- 14.0" diagonal UHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (3840x 2160)
- 14.0" diagonal FHD IPS eDP touch screen with Corning Gorilla Glass 3, 67% sRGB at 220 nits (1920x1080)
- HP SureView Integrated Privacy Display 14.0" diagonal FHD IPS eDP + PSR touch screen with Corning Gorilla Glass 3, 100% sRGB at 700 nits with ambient light sensor Touch (1920x1080)

External

Up to 30-bit (2^30) per pixel "Deep Color" (total of 1,073,741,824 color variations)



Features

HDMI 1.4b

Supports resolution up to 4k @ 24 Hz

Without HP Thunderbolt Dock G2:

HP ZBook 14u with hybrid graphics and without the use of a dock supports up to a maximum of three independent displays. These three displays are the internal panel plus two external displays connected two of the three following ports: HDMI 1.4, Thunderbolt™ 3, Thunderbolt™ 3. HP ZBook 14u configuration with Intel® integrated graphics and without the use of a dock supports up to a maximum of three independent displays. Any three display combination of the system panel plus 2 of the following HDMI, Thunderbolt™ 3, Thunderbolt™ 3.

With HP UltraSlim Dock G2:

Supports up to 2 independent displays when docked on the HP Ultraslim Dock - Max. resolution = 2.5K @ 60Hz (DP1) & 2.5K @ 60Hz (DP2)11

With HP Thunderbolt Dock G2:

The HP Thunderbolt Dock G2 has Thunderbolt™ 3 port, VGA, two DisplayPort™ 1.3, and a USB-C port. When used together with the HP ZBook 14u configuration with hybrid graphics, a maximum of three independent displays are supported. These three displays are internal panel and two external displays connected to the ZBook dock's Thunderbolt™ 3, VGA, or two DisplayPort™ ports. When used together with the HP ZBook 14u configuration with Intel® integrated graphics, a maximum of three independent displays are supported. Any three display combination of the system panel, system ports and ZBook Dock ports. Max. resolution = 4K @60Hz (DP1) & 4K @60Hz (DP2) with Thunderbolt

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.



Features

STORAGE AND DRIVES

One (1) dedicated M.2 drive slots, supporting up to 2 TB of storage

M.2 SATA Solid State Drive 128 GB SATA Solid State Drive

512 GB SATA TLCFIPS-140-2 Solid State Drive

HP Z Turbo Drive (NVMe PCIe SSD)
256 GB PCIe (NVMe) TLC Solid State Drive
512 GB PCIe (NVMe) TLC Solid State Drive
1 TB PCIe (NVMe) TLC Solid State Drive
2 TB PCIe (NVMe) TLC Solid State Drive
256 GB PCIe (NVMe) TLC Self Encrypting (SED) Solid State Drive
512 GB PCIe (NVMe) TLC Self Encrypting (SED) Solid State Drive
256 GB PCIe (NVMe) MLC Solid State Drive
512 GB PCIe (NVMe) MLC Solid State Drive
1 TB PCIe (NVMe) MLC Solid State Drive

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.



Features

DRIVE CONTROLLERS

M.2 Storage Bay (SATA): SATA-3 for Solid State Drive

HP Z Turbo Drive: PCIe Gen 3 x 4 lanes NVMe Solid State Drive

RAID: Not supported

MEMORY

Standard

Up to 32 GB DDR4 1.2V Non ECC SDRAM

Transfer rates up to 2133MT/s on Intel Kaby Lake Chipset or Transfer rates up to 2400MT/s on Intel Kaby Lake – R Chipset Two SODIMM slots supporting dual-channel memory 4 GB, 8GB and 16 GB SODIMMs

Maximum

Upgradeable to 32768 MB with optional 16384 MB SODIMMs in 2 slots

Dual-channel

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

* Maximum memory capacities assume Windows 64-bit operating systems or Linux. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Communications

Intel® I219-LM Gigabit* Network Connection (vPro configurations)
Intel® I219-V Gigabit* Network Connection (non-vPro configurations)

* The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Wireless

Secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth is also available (factory configurable only) combined with the supported wireless LAN option.

802.11 Wireless LAN*

Intel® Dual Band Wireless-AC 8265 802.11 ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (vPro) Intel® Dual Band Wireless-AC 8265 802.11 ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (non-vPro) Realtek RTL8822BE 802.11 ac (2x2) WiFi + Bluetooth 4.2 Combo Adapter*

Wireless WAN - Mobile Broadband **



Features

lintel XMM 7360 LTE-Advanced Broadband Module (optional) HP It4132, LTE/HSPA+ 4G Mobile Broadband Module (optional)

Miracast***

Native Miracast Support

Near Field Communications (NFC)

NXP NPC300 Near Field Communication Module (optional)

- * Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.
- ** WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.
- *** Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming

AUDIO/MULTIMEDIA

Audio

Audio custom tuned by HP and Bang and Olufsen audio Integrated stereo speakers

Integrated HP World Facing icrophone (dual-microphone array when equipped with optional webcam)

Button for volume mute; function keys for volume up and down

Combo mic-in / stereo headphone-out jack

Webcam

720 HD webcam

720 HD webcam with infrared imaging (IR) - (optional)

- Microsoft Hello Certification: Microsoft face authentication in Windows 10 is an enterprise-grade identity verification mechanism
- Microsoft Skype for Business1 Certified
- HD format (widescreen 16:9)
- · Supports videoconferencing and still image capture
- High quality fixed focus lens
- · Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing
- · Improved low light sensitivity
- Improved dynamic range

HP Privacy Camera Shutter (only available on non-touch configurations)

* HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Kevboard

Optional backlit HP Collaboration Keyboard with Function key control to toggle backlit brightness setting - off/full/half brightnessThe HP spill-resistant keyboard is designed using a thin layer of Mylar film under the keyboard and a drain system that funnels fluid through a hole in the bottom of the notebook. This minimizes the risk of damage to sensitive components



Features

underneath. The 86-key compatible keyboard features a full-pitch key layout with desktop keyboard features, such as editing keys, both left and right control and alt keys, function keys, and 18.7 x 18.4 mm key pitch (center-to-center spacing). U.S. and International key layouts are available. Other features include hot keys for instant access to power conservation and brightness.

Pointing Devices

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support Dual Point Stick

Function Keys

Function keys provide control of the following features: standby mode, external display, volume down, volume up, and display brightness.

- F1 Display Switching
- F2 Blank or SureView
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Numlk
- F11 Wireless
- F12 Calendar
- >Share/Present
- >Call Answer
- >Call End

Hidden Fuctions

Fn+R = Break

Fn+S = Sys Rq

Fn+C = Scroll Lock

SOFTWARE AND SECURITY

- 1. Requires Intel® 7th generation processors or greater
- Available on HP Elite and Z products equipped with Intel® 7th generation processors or greater
- 3. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88. Supported on Elite and Z platforms with BIOS version F.03 or higher
- 4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 5. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to http://www.hp.com/go/mobileconnect
- 6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast



Features

- Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/eprintcenter). Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
- 8. Skype is not offered in China.
- 9. Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 10. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 11. Subscription required.
- 12. Requires Windows and Internet Access
- 13. Requires Windows and Intel® or AMD 8th generation processors.
- 14. Opt in and internet connection required for updates.
- 15. HP WorkWise smartphone app is available as a free download on the App Store and Google Play. As of September 2017, HP WorkWise will no longer support iOS or iPhone® devices.
- 16. HP BIOSphere Gen4 features may vary depending on the PC platform and configurations requires 8th Gen Intel® processors.
- 17. Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88. Supported on Elite platforms with BIOS version F.03 or higher.
- 18. HP Sure Start Gen4 is available on HP EliteBook products equipped with Intel® 8th generation processors
- 19. HP Fingerprint Sensor sold separately or as an optional feature.
- 20. RAID configuration is optional and does require a second hard drive.
- 21. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer and Chromium™. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.
- 22. HP Sure Run is available on HP Elite products equipped with Intel® or AMD® 8th generation processors
- 23. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD processors and requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data

Workstation ISV Certifications

Find the latest list of certifications at: http://www.hp.com/go/isv

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

Get the most out of your HP Workstation on day one—and every day thereafter. Designed for all users regardless of technical background, this ultra-savvy software wizard is the simplest and most effective way to make sure your computer is always operating at its optimum potential.

Download at: http://www.hp.com/go/performanceadvisor

Security

See Software section above.

Other Standard Security Features

Integrated Smart Card ReaderOne-Step Logon Security lock slot Support for Intel® AT

Optional Security Features

HP Fingerprint Sensor (optional)

Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS



Features

technology. GPS functionality requires HP Mobile Broadband Module.

* The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.

HP CENTRAL MANAGEMENT

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidently compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks.

An optional fingerprint reader and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.



Features

POWER

Power Supply

HP Smart 45 W External AC power adapter42
HP Smart 45 W External AC power adapter, 2-prong (Japan only)42
HP Smart 65 W External AC power adapter42
HP Smart 65 W EM External AC power adapter42
45 W USB Type-C™ adapter42
65 W USB Type-C™ adapter42

Primary Battery

HP Long Life 3-cell Lithium Polymer Battery (50 WHr) supporting HP Fast Charge Technology

Power Cord

2-wire plug - 1.0m (Japan only)42 3-wire plug - 1.0m42 3-wire plug - 1.8m42 Duckhead power cord - 1.0m42 Duckhead power cord - 1.8m42

HP 65W Slim Smart AC Adapter

Battery Life

Battery life up to 10 hours *

NOTE: Battery is internal and not replaceable by the customer

System Standby Time

Up to 1 weeks**

*Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark https://bapco.com/products/mobilemark-2014/ for additional details.
** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

AMD® Polaris™ Technology Hibernation Standby ACPI compliance

ENVIRONMENTAL

US ENERGY STAR®
IT ECO declaration

EPEAT® registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

NOTE: This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks.



Features

WEIGHTS & DIMENSIONS

Weight

Starting at 3.27 lb (non-touch); Starting at 3.56 lb (touch)45 Starting at 1.48 kg (non-touch); Starting at 1.61 kg (touch)45

Dimensions (w x d x h)

Non-touch

12.84 x 9.22 x 0.7 in 32.6 x 23.4 x 1.79 cm

Touch

12.22 x 9.03 x 0.71 in 31 x 22.93 x 1.81 cm

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes 3 cell 46Whr battery, without hard drive and with 256 GB Z Turbo Drive (PCIe SSD).

PORTS/SLOTS

Ports

Left side:

- (1) USB 3.0 Charging Port
- (1) Security lock slot

Right side:

- (1) Thunderbolt 3™
- (1) USB 3.0 Port
- (1) Headphone/Microphone Combo
- (1) RJ-45 / Ethernet
- (1) Side Docking connector
- (1) Power connector
- (1) SIM Card Slot

Digital Media Slots

(1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have the same 1-year or 3-year limited warranty as the platform. 24/7 operation will not void the HP warranty. Optional HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending
on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP
services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the
time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights
are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your
HP Product. Consult your local HP Customer Support Center for details.



HP ZBook 14u G5 Mobile Workstation

QuickSpecs

Features



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Nominal Operating 19.5 V dc @ 3.3 A

Requirements (AC Power) Voltage

Average Operating Power Windows® 10 (64-bit)

AMD FirePro™ Graphics

Max Operating Power < 45 W with UMA

< 65 W with discrete

Temperature Operating 32° to 95° F (0° to 35° C) (not writing optical)

41° to 95° F (5° to 35° C) (writing optical)

Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine

Non-operating 200 G, 2 ms, half-sine

Random Vibration Operating 0.75 grms
Non-operating 1.50 grms

Altitude (unpressurized) Operating -50 to 10,000 ft. (-15.24 to 3,048 m)

Non-operating -50 to 15,000 ft. (-15.24 to 12,192 m)

Planned Industry Standard Certifications UL Yes
CSA Yes
FCC Compliance Yes

ENERGY STAR® Select models* **EPEAT®** Gold target**

ICES Yes
Australia / Yes
NZ A-Tick Compliance

CCC Yes
Japan VCCI Compliance Yes
KCC Yes
BSMI Yes
CE Marking Compliance Yes

MIL STD*** Passed 14 Mil STD Tests

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.



^{*} Configurations of the HP ZBook 14u G5 that are ENERGY STAR® certified are identified as HP ZBook 14u G5 ENERGY STAR® on HP websites and on http://www.energystar.gov.

^{**} EPEAT registration varies by country. See http://www.epeat.net for registration status by country. EPEAT status listed above applies to U.S.

^{***} MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

Technical Specifications – Displays

DISPLAYS

14.0" diagonal LED AG backlight FHD eDP + PSR H) (1920 x 1080) (400 nits) 100% sRGB

Outline Dimensions (W x 316.11 x 197.98 (mm) max.

Active Area 309.31 x 173.99 (mm)

Weight <285g max. **Diagonal Size** 14.0 (inch) **Thickness** 3.0mm max.

Interface eDP 1.3 + PSR (2 lane)

Panel Technology IPS

Surface Treatment Anti-Glare (AG)

Touch enabled No

Contrast Ratio 600:1 (typical)

Refresh Rate 60 Hz

Brightness 400 nits typical (panel only)

Pixel Resolution Format 1920 x 1080 (FHD)

> Configuration **RGB**

Backlight LED

Color Gamut Coverage 100% sRGB **Color Depth** 6 bits + Hi FRC

PPI 157

Viewing Angle UWVA 85/85/85/85

14.0" diagonal LED backlight FHD IPS eDP touch screen with Corning Gorilla Glass 3 (1920 x 1080) (220 nits) 67% sRGB

H)

Outline Dimensions (W x 316.112 x 197.98 max. (w/ PCB)

Active Area 309.312 x 173.988(mm)

Weight <413g max. **Diagonal Size** 14.0 - inch **Thickness** 3.2mm max. Interface eDP 1.2

IPS Panel Technology **Surface Treatment** Corning Gorilla Glass 3

Touch enabled Yes

Contrast Ratio 600:1 (typical)

Refresh Rate 60 Hz

Brightness 220 nits typical (panel only)

Format 1920 x 1080 (FHD) **Pixel Resolution**

Configuration **RGB**

Backlight LED Color Gamut Coverage 67% sRGB **Color Depth** 6 bits + Hi FRC

PPI 157

UWVA 85/85/85/85 **Viewing Angle**



Technical Specifications - Displays

HP SureView Integrated Privacy Display 14.0" diagonal LED backlight FHD IPS Touch Screen with Corning Gorilla Glass 3 eDP + PSR (1920 x 1080) (700 nits) 100% sRGB Outline Dimensions

(W x H)

315.41x 196.14 (mm) max.

Active Area 309.31 x 173.99 (mm)

Weight <225g max.

Diagonal Size 14.0 – inch

Thickness 3.0mm max.

Interface eDP 1.4a + PSR (2 lane)

Panel Technology IPS

Surface Treatment Corning Gorilla Glass 3

Touch enabled Yes

Contrast Ratio "Privacy mode 150:1 (typ.) – Privacy, 110:1(min.) - Privacy

Refresh Rate 120 Hz

Format 1920 x 1080 (FHD)

Configuration RGB

Backlight LED

Color Gamut Coverage 100% sRGB **Color Depth** 6 bits + Hi FRC

PPI 157

Viewing Angle Privacy mode CR>2: UWVA 50/50/85/85



Technical Specifications – Storage

STORAGE AND DRIVES*

128 GB M.2 SATA TLC Solid State Drive

Drive Weight 0.02 lb (10g) **Capacity** 128 GB

 Height
 0.09 in (2.3mm)

 Width
 0.87 in (22mm)

 Interface
 ATA-8, SATA 3.0

NAND Type TLC Form Factor I/O M.2 2280

Performance Maximum Sequential Read Maximum Sequential Write

Up to 520 MB/s Up to 450 MB/s

Logical Blocks 250,069,680

Operating Temperature 32 to 158F (0 to 70C) [ambient temp]

Features DIPM; TRIM; DEVSLP

512 GB M.2 SATA Self-Encrypting Drive TLC Solid State Drive **Drive Weight** 0.02 lb (10 g) **Capacity** 512 GB

 Height
 0.09 in (2.23 mm)

 Width
 0.87 in (22 mm)

 Interface
 ATA-8, SATA 3.0

NAND Type TLC Form-Factor (I/O) M.2 2280

Performance Maximum Sequential Read Maximum Sequential Write

Up to 530 MB/s Up to 515 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLP

HP Z Turbo Drive 1 TB M.2 Drive Weight
NVMe MLC Solid State Capacity
Drive

 Drive Weight
 0.02 lb (10 g)

 Capacity
 1024 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

NAND Type MLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Drive Weight 0.02 lb (10 g)

Performance Maximum Sequential Read Maximum Sequential Write

Up to 3,000 MB/s Up to 2,900 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option),TRIM; L1.2

HP Z Turbo Drive 512 GB, M.2 NVMe MLC Solid State Drive

 Drive Weight
 0.022 lb (10 g)

 Capacity
 512 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

NAND Type MLC Form-Factor (I/O) M.2 2280

Technical Specifications – Storage

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Up to 3000 MB/s Up to 1500MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (option), TRIM; L1.2

HP Z Turbo Drive 256 GB, Drive Weight
M.2 NVMe MLC Solid Capacity
State Drive

Drive Weight 0.02 lb (10 g) **Capacity** 256 GB

 Height
 0.09 in (2.23 mm)

 Width
 0.87 in (22 mm)

NAND Type MLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Up to 3,100 MB/s Up to 1,400 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TRIM; L1.2

HP Z Turbo Drive 2 TB, Drive We
M.2 NVMe TLC Solid State Capacity
Drive

Drive Weight 0.02 lb (10 g)

Capacity 2 TB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

2,900 MB/s 2,100 MB/s

Logical Blocks 3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; DIPM; TRIM; DEVSLP

HP Z Turbo Drive 1 TB,
M.2 NVMe TLC Solid State
Drive

Unicht

Drive Weight 0.02 lb (10g)

apacity 1 TB

 Height
 0.09 in (2.3mm)

 Width
 0.87 in (22mm)

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Logical Blocks 2,000,409,264

Operating Temperature 32 to 158F (0 to 70C) [ambient temp]

Features TRIM; L1.2

Technical Specifications – Storage

HP Z Turbo Drive 512 GB, Drive Weight
M.2 NVMe TLC Solid State Capacity
Drive

Drive Weight 0.02 lb (10g)
Capacity 512 GB

 Height
 0.09 in (2.3mm)

 Width
 0.87 in (22mm)

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Drive Weight 0.02 lb (10 q)

Performance Maximum Sequential Read Maximum Sequential Write

Logical Blocks 1,000,215,216

Operating Temperature 32 to 158F (0 to 70C) [ambient temp]

Features TRIM; L1.2

HP Z Turbo Drive 256 GB, Drive Weight
M.2 NVMe TLC Solid State Capacity
Drive Height

Drive Weight 0.02 lb (10 g)
Capacity 256 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Up to 2,600 MB/s Up to 900 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TRIM; L1.2



Technical Specifications – Storage

HP Z Turbo Drive 512 GB, Drive Weight
M.2 NVMe SelfEncrypting TLC Solid
State Drive

Height

 Drive Weight
 0.02 lb (10 g)

 Capacity
 512 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Up to 2,600 MB/s Up to 1,400 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TRIM; OPAL 2; L1.2

HP Z Turbo Drive 256 GB, Drive Weight
M.2 NVMe Self- Capacity
Encrypting TLC Solid
State Drive Height

 Drive Weight
 0.02 lb (<10g)</td>

 Capacity
 256 GB

Height 0.14 in (3.58mm)- 0.09 in (2.23mm)

Width 0.87 in (22mm)

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Up to 530 MB/s Up to 515 MB/s

Logical Blocks 500,118,192

Operating Temperature 32 to 158F (0 to 70C) [ambient temp] **Features** ATA Security (Option); TRIM; OPAL 2; L1.2



^{*} For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.

Technical Specifications – Security

SECURITY

HP Fingerprint Sensor Voltage 3.0 - 3.6 VOperating temperature 14° - 167°F (-10° - 75°C) **Current consumption image** 36mA Low latency wait for finger 950 uA 3000 lines/sec **Capture rate ESD Resistance** IEC 6100-4-2 4B (+/-15KV) **Detection Matrix** 200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm **Smart Card Reader** Smart card standard PC/SC 2.0 for Windows smart card standard Dimensions (L x W x H) 0.41x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm) Smart Card support ISO 7816 Class A and AB smart cards **Smart Card Interface** Smart Card Interface with T = 0 and T = 1 support Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM

Features

Operating systems

suspended with smart card present: 380 µA After being suspended without smart card present: 380 µA **Power Saving Mode**: With card present, before being suspended: 40.6 mA Without card present: 380 µA After being suspended with

Normal Mode With card present, before being suspended: 40.9 mA Without card present, before being suspended: 33.16 mA After being

smart card present: 380 µA
• Support single slot
• Support TO, T1 protocol

• Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436.

• SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM

Support ISO7816 Class A, B and C (5V/3V/1.8V) card

• Implemented as an USB full speed device with bulk transfer endpoint, Mass

• Storage endpoint

• Built-in PLL for USB and Smart Card clocks requirement

• Support EEPROM for USB descriptors customization (PID/VID/ iManufacturer/iProduct/Serial Number), Direct Web Page Link, and accessing memory card module.

• EEPROM programmable via USB interface

• Support software update for memory card module

• Support Direct Web Page Link via configuration in external EEPROM

Support short APDU and extended APDU

• Compatible with Microsoft USB-CCID driver

• Support remote wake up through inserting card/removing card

• Support USB selective suspend

• Support Power Saving Mode (Using one pin to select between Normal/PWR Saving Mode)

• Support card power over current protection mechanism

• Built in resonator.

• Support USB LPM (Link Power Management) features.

• Embedded clock source.



Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel® I219-LM Gigabit Network Connection (vPro configurations) **Ethernet Features**

10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-

14)

100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses

13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses

21-30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023.

Clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and

100 Mbit/s

IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE(Energy Efficient Ethernet)

Jumbo Frame 9K

Auto MDI/MDIX Crossover cable detection ACPI compliant - multiple power modes

PowerACPI compliant - multiple power modesManagementEnergy Detect Low Power Mode(Green Ethernet)PerformanceTCP/IP/UDP Checksum Offload (configurable)

Features Protocol Offload(ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling MACSec Offload (802.3ae)

Intel® vPro iSCSI Boot

RSS is kernel based support (e.g. in Win Server 2013)

Ultra Low Power at cable disconnect (<1mW) enables platform

support for connected standby.

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and

Microsoft Wake-Up Frame): Wake-on-LAN from off (Magic Packet

only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Interface PCI Express 1.1 x1 to fully support ASPM LOS/L1 and CLKREO.

NOTE: Intel® I219-LM Gigabit interface is not PCIe compliant. It

operates at half of PCIe specification V1.1 (2.5GT/S) speed.

NIC Device Driver Name Intel® Ethernet Network Connection I219-LM



Technical Specifications – Networking

Intel® I219-V Gigabit Network Connection (Non-vPro configurations) **Ethernet Features** 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses

13-14)

100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3

clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3

clauses 21-30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023.

Clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10

and 100 Mbit/s

IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE(Energy Efficient Ethernet)

Jumbo Frame 9K

Auto MDI/MDIX Crossover cable detection

Power ACPI compliant - multiple power modes

ManagementEnergy Detect Low Power Mode(Green Ethernet)PerformanceTCP/IP/UDP Checksum Offload (configurable)

Features Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling MACSec Offload (802.3ae)

Intel Non-vPro iSCSI Boot

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and

Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet

only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Interface PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ.

NOTE: Intel® 82579 PCIe interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.

NIC Device Driver Name Intel® 82579LM/82579V Ethernet Network Connection



Technical Specifications - Networking

HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module

Technology/Operating

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz,

bands 850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz,

800 (Band 20), 700 (Band 28) MHz.

HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4

and MSC1 - MSC9

GPS Standalone, A-GPS (MS-B and LTO)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power

LTE: 23 dBm HSPA+: 23.5 dBm

E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)

Form Factor

M.2, 3042-S3 Key B

Weight 6 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel®XMM™ 7360 LTE-Advanced

Technology/Operating

bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 20), 2100 (Band

5), 900 (Band 8) MHz

Wireless protocol standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz

throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS Bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Maximum Data Rates LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload)

HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)



Technical Specifications – Networking

Maximum Output Power LTE: 23 dBm HSPA+: 23.5 dBm

Maximum Power LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Consumption

Form Factor M.2, 3042-S3 Key B

Weight 5.8q

Dimensions 1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x Thickness)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors.

IEEE 802.11a

IEEE 802.11b

IEEE 802.11q

IEEE 802.11n

IEEE 802.11n

Intel® Dual Band **Wireless LAN Standards** Wireless-AC 8265 802.11 AC/a/b/q/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (vPro)

Wi-Fi certified Interoperability

Frequency Band 802.11b/g/n 2.402 - 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise

disable those channels

802.11a 4.9 - 4.95 GHz (Japan)

> 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz

(CH149 - CH161)

Data Rates 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and

80MHz)

Modulation Direct Sequence Spread Spectrum

CCK, BPSK, QPSK, 16-QAM, 64-QAM, 256-QAM

Security¹

IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI



Technical Specifications – Networking

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between band Access Points

Output Power² • 802.11b: +16dBm minimum

802.11g: +14dBm minimum802.11a: +14dBm minimum

802.11n HT20(2.4GHz): +13dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +12dBm minimum 802.11n HT40(5GHz): +12dBm minimum

Power Consumption Transmit: 2.0 Watts (max)

Receive: 1.6 Watts (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connect Standby: 10mW (WLAN + BT)

Radio disabled: 5 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -94dBm maximum

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -88dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 2SS, MCS-9: -61dBm maximum 802.11ac, 2SS, MCS-9: -58dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

0r

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230: 2.8g

0r

Type 1630 : 2g 3.3v +/- 9%

Operating Voltage 3.3v +/- 9%
Temperature Operating

Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

Technical Specifications – Networking

Intel® Dual Band Wireless-AC 8265 802.11 AC/a/b/g/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (non-vPro) Wireless LAN Standards IEEE 802.11a IEEE 802.11b

IEEE 802.11g IEEE 802.11n

IEEE 802.11ac
Interoperability Wi-Fi certified

Frequency Band 802.11b/g/n 2.402 - 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise

disable those channels

• 4.9 - 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

• 5.25 - 5.35 GHz

• 5.47 - 5.725 GHz

• 5.825 - 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161

Antenna Structure Data Rates 2 transmit; 2 receive (2x2)

802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: card will support rates for NSS=1 and NSS=2 for RX and TX for 20 and 40 MHz channels. Short and long guard interval shall be supported.

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation Security¹

- IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

Network Architecture Models

Roaming

Output Power²

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

- 802.11b: +16dBm minimum
- 802.11g: +14dBm minimum
- 802.11a: +14dBm minimum
- 802.11n HT20(2.4GHz): +13dBm minimum
- 802.11n HT40(2.4GHz): +13dBm minimum
- 802.11n HT20(5GHz): +12dBm minimum



Technical Specifications – Networking

802.11n HT40(5GHz): +12dBm minimum

802.11ac 80MHz(5GHz): +11dBm minimum

Power Consumption Transmit: 2.0 W (max)

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

802.11g:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), -Receiver Sensitivity³

85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76

dBm (48 Mbps), -74 dBm (54 Mbps)

802.11b:-95 dBm (1 Mbps), -93 dBm (2 Mbps), -91 dBm (5.5 Mbps),

-88 dBm (11 Mbps)

802.11q:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), -

85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76

dBm (48 Mbps), -74 dBm (54 Mbps)

802.11n:-69 dBm (150 Mbps), -66 dBm (300 Mbps)

High efficiency antenna with spatial diversity, mounted in the Antenna type

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express Half-MiniCard

Dimensions 0.134 x 1.06 x 1.18 in (3.4 x 26.8 x 30 mm)

Weight 3.1q

3.3v +/- 9% Operating Voltage

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

> Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft. (3,048 m)

> Non-operating 0 to 50,000 ft. (15,240 m)

LED Activity LED Amber - Radio OFF; LED White - Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications – Networking

Realtek RTL8822BE 802.11ac 2x2 Wi-Fi + BT4.2 Combo Adapter Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac

Interoperability
Frequency Band

Wi-Fi certified 802.11b/g/n

2.402 - 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels

802.11a

4.9 - 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

5.25 - 5.35 GHz

• 5.47 - 5.725 GHz

5.825 - 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)

Data Rates

802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: card will support rates for NSS=1 and NSS=2 for RX and TX for 20 and 40 MHz channels. Short and long guard interval shall be supported.

802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and

80MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security¹

 IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

• IEEE 802.11i

 Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models

Roaming

Output Power²

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

TX Power(dBm)	Min	Typical	Max
802.11b	+14	+15.5	
802.11g	+12	+13.5	



Technical Specifications - Networking

802.11a	+12	+13.5	
802.11n HT20(2.4GHz)	+12	+13.5	
802.11n HT40(2.4GHz)	+12	+13.5	
802.11n HT20(5GHz)	+10	+11.5	
802.11n HT40(5GHz)	+10	+11.5	
802.11ac VHT80(5GHz)	+10	+11.5	

Power Consumption Transmit: 2.0 W (max)

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connect Standby: 10 mW (WLAN+BT)

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³

RX Sensitivity(dBm)	Min	Typical	Max
802.11b, 1Mbps		-95	-93.5
802.11b, 11Mbps		-85.5	-84
802.11a/g, 6Mbps		-87.5	-86
802.11a/g, 54Mbps		-73.5	-72
802.11n, MCS07		-68.5	-67
802.11n, MCS15		-65.5	-64
802.11ac, MCS0		-85.5	-84
802.11ac, MCS9		-60.5	-59

Antenna type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230: 2.8g

0r

Type 1630 : 2g

Operating Voltage 3.3v +/- 9%

Temperature

Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)



Technical Specifications – Networking

Altitude 0 to 10,000 ft (3,048 m) Operating

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF; LED White - Radio ON

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth® 4.2 Wireless Technology

Bluetooth® Specification 4.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of +4 dBm for BR and EDR

Receiver Sensitivity

Modulation	0.01% BER	0.001% BER
GFSK	-80 dBm	-70 dBm
π/4-DQPSK	-80 dBm	-70 dBm
8DPSK	-80 dBm	-70 dBm

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Antenna Internally integrated within module

Range Legacy Up to 33 ft (10 m)

BLE Up to 99 ft (30 m)

Electrical Interface USB 2.0 compliant

Bluetooth® Software

Supported

Microsoft Windows Bluetooth Software

Link Topology Point to Point, Multipoint Pico Nets up to 7 slaves Security Full support of Bluetooth Security Provisions **Power Management** Microsoft Windows ACPI, and USB Bus Support

Certifications

Self-configurable to optimize power conservation in all operating

modes, including Standby, Hold, Park, and Sniff

All necessary regulatory approvals for supported countries, Security

ETS 300 328, ETS 300 826

including:

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power management

certificactions Low Voltage Directive IEC950

UL, CSA, and CE Mark

Technical Specifications – Networking

Certifications Serial Port Profile (SPP)1

Bluetooth® Profiles Supported Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)1,2

Generic Object Exchange Profile (GOEP)1,2

Object Push Profile (OPP)1,2

Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1,2 Human Interface Device Profile (HID)1,2

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP) Audio Video Remote Control Profile (AVRCP)

Bluetooth® V4.2 support V4.2: ESR8 compliant, LE Secure Connection – Basic.

feature V4.1: ESR5/6/7 compliant

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows Vista.



Technical Specifications – Networking

Near Field Communications (NFC)

Controller NFC Mirage WNC XRAV-1 (NXP NPC300 I2C 10mmx17mm)

Supports • Windows 10

NFC Forum Compliant

Near Field Communications Controller

Dimensions Module 25 mm by 10 mm by 2.0 mm

(L x W x H)

Chipset NPC300 System interface I2C

NFC RF standards standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2

NFC Forum Support

Tag

Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE

1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards

Card Emulation (PICC-VICC)

Mode¹ ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer Raw RF Data Rates 106, 212, 424, 848 kbps

Operating 0°C to 70°C

temperature

Storage temperature -20°C to 125°C

Humidity 10-90% operating 5-95% non-operating

Supply Operating

voltage

2.97 to 5.5 Volts

I/O Voltage 1.8V or 3.3V

Power Consumption Booster enable, VBAT= 3.3V,

VCC_BOOST = 5V)
Mode Power
Consumption,

Typical² Polling 7.3 mA Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA

Tag Type 3 Total 287.7 mA Net Module 240.7 mA Detected Test Tag Type 4 Total 282.3 mA Net Module

235.3 mA

Antenna connector 0.5

0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

Notes

1. With application or UICC support

2. Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period

configured.



Technical Specifications – Audio

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Hardware Implementation Conexant CX7750

> **Function Key Volume Controls**

Volume up, volume down, and mute

Line In/Line Out Yes, via dock Headphone/Microphone in Yes combo jack

Integrated Microphone Yes, dual digital microphone array when equipped with optional webcam

Audio Output Quality Frequency Response 20 Hz - 20 kHz

> Signal to Noise Ratio >85 dB **Total Harmonic Distortion** 0.01% **Noise Floor** -110 dB Play/Record Sampling Rate(s) 8 kHz - 48kHz DAC 16, 20 or 24-bit

ADC 16,20-bit

Integrated Stereo

Power Rating 2 Watts Speakers 4 Ohms **Impedance**



Technical Specifications – Power

POWER

HP 65W Smart AC Adapter

Dimensions 107.0x47.0x30.0mm Weight unit: 250g +/- 10g Input 90 to 265 VAC

> **Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency

47 to 63 Hz

range

Input AC current Max 1.7 A at 90 Vac

65W **Output Output power**

DC output 19.5V

Hold-up time 5 ms at 115 Vac input

Output current limit <11.0A

AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector)

AC Connector (Ac Inlet) **Environmental Design**

Operating temperature

32° to 95° F (0° to 35° C)

Non-operating

(storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

Output

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter EM **Dimensions** 102.0x55.0x30.0mm Weight unit: 350g +/- 10g 90 to 265 VAC Input

> **Input Efficiency** 87.0% min at 115 VAC and 230Vac

Input frequency

Input AC current

range

47 to 63 Hz

Max. 1.7 A at 90 VAC

65W **Output power**

DC output 19.5V

> 5 ms at 115 Vac input Hold-up time

Output current limit <11.0A

AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector)

AC Connector (Ac Inlet) Operating 32° to 95° F (0° to 35° C) **Environmental Design** temperature



Technical Specifications – Power

Non-operating

(storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Travel AC Adapter

Dimensions 120.0x57.6x16.7mm Weight unit: 250g +/- 10g

Input **Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230Vac

> Input frequency range 47 to 63 Hz **Input AC current** 1.7 A at 90 Vac

Output **Output power** 65W

> DC output 19.5V/5V

Hold-up time 5 ms at 115 Vac input

Output current limit <11.0A

DC Plug 4.5mm/7.4mm tips

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1.

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.



Technical Specifications – Power

HP 45W Smart AC Right Angle Adapter Argentina Weight

Dimensions 3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)

0.386 lb (175g) max

Input **Input Efficiency** 87.74% at 115Vac and 88.4% at 230Vac

> Input frequency range 47 to 63 Hz

Input AC current Max 1.4 A at 90 VAC

Output **Output power** 45W

DC output 19.5V

Hold-up time 5 ms at 115 Vac input

Output current limit <8.0 A

Environmental Design Operating 32° to 95° F (0° to 35° C) temperature

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class 1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

HP 65W Smart AC Adapter Argentina

Dimensions 107.0x47.0x30.0mm Weight unit: 250g +/- 10g Input 90 to 265 VAC

> **Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range

47 to 63 Hz

Input AC current Max 1.7 A at 90 Vac

Output **Output power** 65W

> 19.5V DC output

Hold-up time 5 ms at 115 Vac input

Output current limit <11.0A

AC Connector (Ac Inlet)

C6 (3pin/with grounded, with Smart ID DC connector)

AC Connector (Ac Inlet) Environmental Design

Operating temperature

32° to 95° F (0° to 35° C)

Non-operating

(storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

^{*} MTBF - over 200,000 hours at 25°C ambient condition.

Technical Specifications – Power

EMI and Safety *CE Mark - full compliance with LVD and EMC directives

Certifications * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 45W Smart AC Right Angle Adapter Dimensions 3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)

Weight 0.386 lb (175g) max

Input **Input Efficiency** 87.74% at 115Vac and 88.4% at 230Vac

> Input frequency range 47 to 63 Hz

Input AC current Max 1.4 A at 90 VAC

Output 45W **Output power**

> DC output 19.5V

Hold-up time 5 ms at 115 Vac input

Output current limit <8.0 A

Environmental Design Operating

temperature

32° to 95° F (0° to 35° C)

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 45W Smart AC Adapter (2 Prong) **Dimensions** $(H \times W \times D)$

Weight Input

95.0x40.0x26.5mm unit: 200g +/- 10g 90 to 265 VAC

Input Efficiency 87.74% at 115Vac and 88.4% at 230Vac

Input frequency range 47 to 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45W

DC output 19.5V

Hold-up time 5 ms at 115 Vac input

Output current limit <8.0A

AC Connector (Ac Inlet) Environmental Design

Operating

C8 (2 pin/non-grounded, with Smart ID DC connector) 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

Technical Specifications – Power

Technical Specificat	tions – Power		
	EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.	
HP 45W Smart	Dimensions	62.0x62.0x28.5mm	
USB Type C Adapter	Weight	unit: 220g +/- 10g	
	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 10V: 87.5% 12V: 87.8% 15V: 87.8% 20V: 87.8%
		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.4 A at 90 Vac
	Output	Output power	45W
		DC output	5V/15W; 9V/27W; 10V/37.5W; 12V/45W; 15V/45W; 20V/45W
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<5.0A
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	* Worldwide safety standa SELV; Agency approvals - FCC Class B, CISPR22 Class	· · · · ·
HP 65W Smart	Dimensions	74x74x28.5mm	
FCC Class B, CISPR22 Class B, CCC, NOM-1 * MTBF - over 200,000 hours at 25°C amb HP 65W Smart USB Type C Adapter Weight Input Input Efficiency 81.5% min at 88% min at 1 88% min at 1 89% min at 1			
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.7 A at 90 Vac

Output power

DC output

65W

5V/9V/10V/12V/15V/20V

Output

Technical Specifications – Power

Hold-up time 5 ms at 115 Vac input

Output current limit <8.0A

Environmental DesignOperating
temperature

32° to 95° F (0° to 35° C)

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 100,000 hours at 25°C ambient condition.

HP Long Life 3-cell Dimens
Polymer Battery (51WHr) Weight

Dimensions (H x W x L)

6.8mm x 102.8mm x 198mm

Weight 235 g

Cells/Type3cell Lithium-Ion Polymer cell / 506480EnergyVoltage11.55V

Amp-hour capacity 4420mAh Watt-hour capacity 51wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 140° F(-10° to 60° C)

Fuel Gauge LED No

Warranty 1000 cycles > 65% (at 23°C)

Optional Travel Battery

Available

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword *generator* on HP's 3rd party option store for solar energy accessory at http://www.hp.com/go/options.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAP® test method)

/··· ==================================			
STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	9.06 W	9.98 W	9.6 W
Normal Operation (Long idle)	7.31 W	7.82 W	8.0 W
Sleep	0.76 W	0.89 W	0.75 W
Off	0.44 W	0.56 W	0.43 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	31 BTU/hr	34 BTU/hr	33 BTU/hr
Normal Operation (Long idle)	25 BTU/hr	27 BTU/hr	27 BTU/hr
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr
Off	2 BTU/hr	2 BTU/hr	1 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions	Sound Power	Sound Pressure
(in accordance with	(L _{WAd} , bels)	(L _{pAm} , decibels)
ISO 7779 and ISO 9296)		
Typically Configured – Idle	2.9	20
Fixed Disk – Random writes	2.9	21

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC



Technical Specifications - Environmental

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 7.8% post-consumer recycled plastic (by wt.)
- This product is 96.1% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Cardboard & misc	360.2 g
Internal:	PLASTIC/EPE (Expanded Polyethylene)	29.8 g
	PLASTIC/Polyethylene low density	13.6 g
	PLASTIC/Polypropylene	6 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, has been voluntarily removed from most applications.



Technical Specifications - Environmental

- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Country of Origin

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Memory	HP 4GB DDR4-2400 SODIMM (Core processors only)	Z4Y84AA
	HP 16GB DDR4-2400 SODIMM (Core processors only)	Z4Y86AA
Cases	HP Executive 15.6 Black Top Load	P6N18AA
	HP Business Case (up to 15.6")	H5M92AA
Docking	HP UltraSlim Docking Station	D9Y32AA
	HP 2013 UltraSlim Docking Station TAA (US only)	E5C22AV#ABA
	HP Executive Travel Hub	T0K29AA
	HP Travel Hub	T0K30AA
	HP 3005pr USB 3.0 Port Replicator w/ USB-C Adapter	Y4H06AA
	HP Display and Notebook Stand II	E8G00AA#xxx
	HP USB-Type C™ Elite Dock	X7W54AA
Input/Output -	HP Comfort Grip Mouse	H2L63AA
Mice	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP Ultrathin Wireless Mouse	L9V78AA
	HP USB Travel Mouse	G1K28AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
	HP USB Essential Keyboard and Mouse	H6L29AA#xxx
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA#xxx
Power Adapters	HP 65W Slim A/C Adapter w/USB	H6Y82AA
	HP 65W Smart AC Adapter	H6Y89AA
Adapters	HP USB-C™ to VGA Adapter	N9K76AA
	HP USB-C to USB 3.0	N2Z63AA
	HP USB-C to USB Hub	Z6A00AA
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA
	HP HDMI to DVI adapter	F5A28AA
	DisplayPort™ to DVI Adapter	F7W96AA
	DisplayPort™ to VGA	F7W97AA
	DisplayPort™ to HDMI 1.4 Adapter	F3W43AA
Collaboration	HP UC Conferencing Keyboard	K8P74AA#xxx
	HP UC Speaker Phone	K7V16AA
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Options and Accessories (sold separately and availability may vary by country)

HP UC Wired Headset	K7V17AA
HP UC Mono Wireless Headset	W3K08AA
HP UC Duo Wireless Headset	W3K09AA
HP Stereo 3.5mm Headset	T1A66AA
HP Stereo USB Headset	T1A67AA

Storage - ExternalHP External USB DVDRW DriveF2B56AAStorageHP 500GB 7200rpm HDDF3B97AA

 HP 256GB M2 NVME PCIe SSD (2280)
 V3K66AA

 HP 512GB M2 NVME PCIe SSD (2280)
 V3K67AA

Security HP Dual Head Cable Lock (Non-Master key) T1A64AA

HP Dual Head Cable Lock (Master Key)

HP Docking Station Cable Lock

HP Essential Combination Lock

HP Combination Lock

TOY15AA

HP Keyed Cable Lock

TOY14AA

NOTE: External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



Summary of Changes

Date of change:	Version History:		Description of change:
February 15, 2018	From v1 to v2	Change	Environmental data updated
February 23, 2018	From v2 to v3	Added	Dock, case, mouse, adapter, display and care packs added to options section
March 1, 2018	From v3 to v4	Added	Battery note on power supply section
May 21, 2018	From V4 to V5	Update	



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